

Title (en)

SILICON TIMEPIECE COMPONENT FOR A TIMEPIECE

Title (de)

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Title (fr)

COMPOSANT HORLOGER EN SILICIUM POUR PIÈCE D'HORLOGERIE

Publication

**EP 4111264 A1 20230104 (FR)**

Application

**EP 21704834 A 20210218**

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Abstract (en)

[origin: WO2021170473A1] The invention relates to a method for manufacturing a timepiece component capable of thermocompensating a functional assembly comprising the timepiece component, characterized in that said method comprises at least the following steps: a. providing (E1) a substrate (1) of semiconductor or metallic material; b. proceeding with the deposition (E2) of a polycrystalline or monocrystalline silicon layer (5) on the substrate (1); c. releasing (E4) the timepiece component (10) from the substrate (1).

IPC 8 full level

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Citation (search report)

See references of WO 2021170473A1

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